



DOCKET NO: 268844US0PCT

"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1765"

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HIROSHI SHIHO, ET AL. : EXAMINER: CHEN, KIN CHAN
SERIAL NO: 10/529,742 :
FILED: JANUARY 6, 2006 : GROUP ART UNIT: 1765
FOR: POLISHING PAD FOR :
SEMICONDUCTOR WAFER AND :
LAMINATED BODY FOR POLISHING OF :
SEMICONDUCTOR WAFER EQUIPPED :
WITH THE SAME AS WELL AS :
METHOD FOR POLISHING OF :
SEMICONDUCTOR WAFER

REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Office Action of June 8, 2007, Applicants request reconsideration
in view of the following remarks.

Remarks begin on page 2 of this paper.